

## CLAIMS:

1. A method for manufacturing a multi-layered ceramic electronic component comprising steps of positioning a multi-layered unit formed on a support sheet and including a release layer, an electrode layer and a ceramic green sheet so that a surface of the multi-layered unit is located on a base substrate, pressing the multi-layered unit toward the base substrate and laminating the multi-layered unit on the base substrate, wherein the base substrate has such surface roughness as to include per 0.01 mm<sup>2</sup> thereof not more than one protrusion that can penetrate the ceramic green sheet of the multi-layered unit laminated on the base substrate to half or more the thickness of the ceramic green sheet and include per 100 mm<sup>2</sup> thereof not more than one protrusion that can completely penetrate the ceramic green sheet.
2. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein an agglutinant layer is formed on the base sheet and the multi-layered unit is positioned on the base substrate so that the surface of the multi-layered unit comes into contact with the surface of the agglutinant layer and pressed toward the base substrate, thereby laminating the multi-layered unit on the base substrate.
3. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the agglutinant layer is formed on the surface of the base sheet in such a manner that the bonding strength between itself and the base substrate is higher than the bonding strength between the support sheet and the release layer and lower than the bonding strength between itself and the ceramic green sheet.

4. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer is formed on the surface of the base sheet in such a manner that the bonding  
5 strength between itself and the base substrate is higher than the bonding strength between the support sheet and the release layer and lower than the bonding strength between itself and the ceramic green sheet.

5. A method for manufacturing a multi-layered ceramic electronic  
10 component in accordance with Claim 2, wherein the agglutinant layer has a thickness of 0.01  $\mu\text{m}$  to 0.3  $\mu\text{m}$ .

6. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 3, wherein the agglutinant layer has  
15 a thickness of 0.01  $\mu\text{m}$  to 0.3  $\mu\text{m}$ .

7. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer has  
20 a thickness of 0.01  $\mu\text{m}$  to 0.3  $\mu\text{m}$ .

8. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer contains a binder belonging to the same binder group as that of a binder contained in the ceramic green sheet belongs to.

25

9. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 3, wherein the agglutinant layer contains a binder belonging to the same binder group as that of a binder

contained in the ceramic green sheet belongs to.

10. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer  
5 contains a binder belonging to the same binder group as that of a binder contained in the ceramic green sheet belongs to.

11. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer  
10 contains a plasticizing agent belonging to the same binder group as that of a plasticizing agent contained in the ceramic green sheet belongs to.

12. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 3, wherein the agglutinant layer  
15 contains a plasticizing agent belonging to the same binder group as that of a plasticizing agent contained in the ceramic green sheet belongs to.

13. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer  
20 contains a plasticizing agent belonging to the same binder group as that of a plasticizing agent contained in the ceramic green sheet belongs to.

14. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the agglutinant layer  
25 contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

15. A method for manufacturing a multi-layered ceramic electronic

component in accordance with Claim 3, wherein the agglutinant layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

5 16. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the agglutinant layer contains dielectric particles having the same composition as that of dielectric particles contained in the ceramic green sheet.

10 17. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

15 18. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and  
20 polyethylene terephthalate.

19. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 3, wherein the base substrate is formed of a plastic material selected from a group consisting of  
25 polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

20. A method for manufacturing a multi-layered ceramic electronic

component in accordance with Claim 4, wherein the base substrate is formed of a plastic material selected from a group consisting of polyethylene, polypropylene, polycarbonate, polyphenylene ether and polyethylene terephthalate.

5

21. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 1, wherein the ceramic green sheet has a thickness equal to or thinner than 3  $\mu\text{m}$ .

10 22. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 2, wherein the ceramic green sheet has a thickness equal to or thinner than 3  $\mu\text{m}$ .

15 23. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 3, wherein the ceramic green sheet has a thickness equal to or thinner than 3  $\mu\text{m}$ .

20 24. A method for manufacturing a multi-layered ceramic electronic component in accordance with Claim 4, wherein the ceramic green sheet has a thickness equal to or thinner than 3  $\mu\text{m}$ .